

FORM PTO-1449 (Modified)

ATTY. DOCKET NO.

SERIAL NO.

END920020027US1

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LIST OF PATENTS AND PUBLICATIONS FOR
APPLICANT'S INFORMATION
DISCLOSURE STATEMENTAPPLICANT: CLÉMENT J.
FORTIN, ET AL.

PAGE 1 OF 1

(Use several sheets if necessary)

FILING DATE:

GROUP: 2813

Reference

US Patent Documents

Designation

EXAMINER INITIALS		DOCUMENT NUMBER	ISSUE DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPRO.)
<i>[Signature]</i>	AA	4,339,785	07/13/82	OHSAWA	361	411	04/08/80
<i>[Signature]</i>	AB	5,085,364	02/04/92	ISHIKAWA, ET AL.	228	139	09/05/90
<i>[Signature]</i>	AC	5,128,746	07/07/92	PENNISI, ET AL.	357	72	09/27/90
<i>[Signature]</i>	AD	5,493,259	02/20/96	BLALOCK, ET AL.	333	182	03/06/95
<i>[Signature]</i>	AE	5,529,957	07/25/96	CHAN	437	250	04/06/95
<i>[Signature]</i>	AF	5,814,401	09/29/98	GAMOTA, ET AL.	428	343	02/04/97
<i>[Signature]</i>	AG	6,071,371	06/06/00	LEONARD, ET AL.	156	297	02/02/98
<i>[Signature]</i>	AH	6,202,917B1	03/20/01	WEAVER, ET AL.	228	180	08/19/98
	AI						
	AJ						
	AK						

Foreign Patent
Documents

<i>[Signature]</i>	AL	JP401100993A	04/19/89	AKIYAMA	H05K3	34	10/14/87
	AM						
	AN						
	AO						

OTHER ART (Including
Author, Title, Date,
Pertinent Pages, etc.)

[Signature] AP AMICON® E 1350 Series, "No Flow-Fluxing Underfill Encapsulants for Flip Chip Devices",
Emerson & Cuming, Specialty Polymers.

[Signature] AQ SE-CURE® 9101 "Reflow Encapsulant", Kester Solder, Polymer Products Group.

[Signature] AR STAYCHIP™, NUF-DP0071 - No Flow Underfill, Developmental Product Information.

[Signature] AS DEXTER, HYSOL® FF 2200, "Reflow Encapsulant".

[Signature] AT DEXTER, HYSOL® FluxFill™ 2000, "Reflow Encapsulant".

EXAMINER

DATE CONSIDERED

6/9/05

EXAMINER: Initial if reference considered,
whether or not citation is in conformance
with MPEP 609. Draw line through citation
if not in conformance and not considered.
Include copy of this form with next
communication to applicant.